

ASTM 2240

ASTM D2566

2 ISTM D570

ASTM 638

² ISTM D189

2 ISTM D366

3 ASTM 638

² ISTM D696

ASTM 638

Uni-Seal[™] 3718F

UV/Visible Light/Heat/Activator Curable Flexible Low Shrink Encapsulant

PRODUCT DESCRIPTION

Incure Uni-Seal[™] 3718F UV/Visible Light/LED curable adhesive is a encapsulant for electronic components on printed circuit boards. Product can be cured in seconds, with optional secondary heat cure. Exhibits low stress and low shrinkage properties during cure and is often used as a moisture barrier for sensitive components. Formulated with enhanced moisture and temperature resistance, with fluorescing feature to aid inspection. It is 100% solids, contains no volatiles and it is ideal for product requiring thermal cycling.

CURED PROPERTIES

Shore Hardness, Durometer

Water Absorption at 24hrs

Tensile (PSI)

* PC-PC / SS-SS / S-S / AL-AL ^ PC Substrate Failure

Elongation at Break

150

Tensile (%)

Surface After Full Cure

Linear Shrinkage / Expansion (-ve)

Thermal Range (Brittleness / Degrades) °C

Young's Modulus of Elasticity, MPa (PSI)

Linear CTE (a1 & a2), ppm/°C

2 ISTM - refers to Incure Standard Test Method

UNCURED PROPERTIES

Chemical Type	Urethane Acrylate, 100% Solids, No Solvents						
Appearance	Single Co	Single Component, Slightly Translucent					
Density, g/ml	1.08	1.08 Refractive Index			@20°C		
Flash Point, °C	> 93	>93 Toxicity Low (Ref			er to MSDS)		
Viscosity, cP	10,000 - 18,000 @20rpm			Spindle	6		
Other viscosities are available upon request. If the viscosity range requested is not our standard offering, this product may be produced with a small lab fee. ASTM D2556 Email us at: support@uv-incure.com or your nearest local distributor for more information.							

¹ Viscosity (cP) taken at 25°C - Call to enquiry for other viscosities

RECOMMENDED UV CURE SCHEDULE (FULL CURE)

Full Cure Ex	UVA	UVB	UVC	UVV		
Fixture Time between glass slides		mW/cm ²	223	56	4	215
Exposure Time (s)	1.0	mJ/cm ²	223	56	4	215
F200P™ @3.75" Dist	5.0	mW/cm ²	223	56	4	215
Belt Speed (ft/min)	12.0	mJ/cm ²	1,115	280	19	1,075
F500™ @3.0" Dist	3.0	mW/cm ²	436	127	12	390
Belt Speed (ft/min)	8.0	mJ/cm ²	1,308	381	35	1,170
S20 [™] Spot (4-Pole LG) 0.4" Dist		mW/cm ²	3,000	530	50	3,400
Exposure Time (s)	1.0	mJ/cm ²	3,000	530	50	3,400
L9000™ LED Spot @ 0.67" Dist		mW/cm ²	2,800	42	12	102
Exposure Time (s)	3.0	mJ/cm ²	8,400	126	36	306

Cure times on 8mm ø adhesive sample. Belt speeds using C9000-F200Px1AB (Flood) and C9000-F500x1AC (Focused Beam) conveyors for area curing. Please consult IncureLab™ for any other requi

UV INTENSITY REFERENCE TABLE

Incure UV Curing Lamp Model	⁴ Curing Distance vs UV Intensity					
Spot Curing (Diameter)	0.5" (12.6)	1" (25.4)	1.5" (38)	2" (50.8)	2.5" (63.5)	3" (76.2)
S20™ ARC (mW/cm²) / (ø mm)	1,400 (3)	1,500 (4)	650 (6)	360 (8)	240 (10)	175 (12)
L9000™ LED (mW/cm²) / (ø mm)	7,500 (9)	5,000 (10)	2,300 (17)	1,200 (20)	700 (25)	450 (30)
Flood/Focus Beam (Area)	UV Intensity (mW/cm ²)					
F200™ ARC Flood (6" x 8")	325	280	245	215	190	165
F400™ ARC Flood (4" x 4")	860	570	440	345	270	215
F500™ ARC Focused (3" x 5")	1,040	685	530	415	325	260
L1044-365™ LED Flood (4" x 4")	2,675	2,380	1,900	1,625	1,430	1,280
L1044-405™ LED Flood (4" x 4")	2,950	2,625	2,150	1,900	1,650	1,450
⁴ Curing Distance is defined by the tip of light-guide or base of lamp housing to the bond area. All values are nominal with ±10%						

variation, with LED Flood Static Uniformity at ±78% and Dynamic Uniformity at ±90%. Recommended curing parameters in grey,

UV CUBING SCHEDULE FOR THIS PRODUCT

Wavength λ	UVA (320 - 400nm)	UVB (290–320nm)	UVC (290-220nm)	VUV (400-700nm)	Note: This product has been thoroughly tested to cure with F200P™ UV Flood Lamp.	
Minimum Intensity	223 mW/cm ²	56 mW/cm ²	4 mW/cm ²		Intensity wavelengths (shaded) are crucial for curing this product. All measurements are made with EIT UV PowerPuck II. If you are unable to fully cure this product for	
Total Energy Required	1,115 mJ/cm ²	280 mJ/cm ²	19 mJ/cm ²		some reasons, pls email us for assistance with your curing information.	

SHELF-LIFE, STORAGE, USE AND HANDLING OF THIS PRODUCT

Shelf-Life of this unopened product is a minimum of SIX (6) months from date of manufacture. Avoid direct exposure of bottle to visible light at all times. Containers should remained covered when not in use. Product should be stored in a dark cool place of 10°C to 32°C. Transfer of product into other packages void all warranties. Users should ensure all bonding surfaces are free of grease, mold release, or any contaminants, as bonding performance will be compromised. All tests for cured bonds should be carried out at ambient temperature. For safe handling of this product, please read Material Safety Data-sheet (MSDS) prior to use. Organic solvents, such as IPA, may be used to wipe away uncured material from surfaces.

EtO and GAMMA STERILIZATION (Not Applicable for this Product)

All Incure medical products are formulated to subject to standard sterilization methods, such as EtO and Gamma Radiation of 25 to 50 kGravs (cumulative). Enhanced moisture and thermal resistance of this product show excellent adhesion and bonding strength after one cycle of steam auto-clave test. Depending on bond design and structure of the application, users should test specific assemblies after subjecting them to sterilisation. Consult Incure Support Team for assistance, if your devices are subjected to more than one sterilization cycles.

NOTE

The data contained in this document are furnished for information only. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein. INCURE will not be liable for any indirect, special, incidental or consequential loss or damage arising from this INCURE product, regardless of the legal theory asserted. INCURE recommends that each user adequately test its proposed use and application before repetitive use, using this data as a guide.

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RoHS Pb HF

	At 1	0min 🗖 At	30min 🗖	At 60min		
112.5					m	-
75						
37.5						
0	-60	-40	22	100	125	155
	-00	-40		rature (°C)	120	100

D40 to D50

2.400* / 4.400*

4,000* / 5,200*

Tack-Free

Not Available

a1=50, a2=74

254%

0.00%

TENSILE STRENGTH VS TEMPERATURE

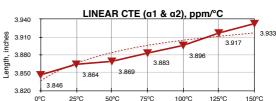
³ ASTM 638 Young's Modulus test speed @5mm/min for rigid and semi-rigid materials, @50mm/min for non-rigid materials, unless otherwise specified.

0.70%

0.60%

PC-PC / SS-SS

S-S / AL-AL





0°C 25°C 50°C 75°C 100°C

SECONDARY HEAT CURE SCHEDULE

Continuous Oven Bake	Duration
95°C (203°F)	120 mins
110°C (230°F)	60 mins
125°C (257°F)	30 mins